



Material Content Data Sheet



Sales Product Name				2EDN7523R		Issued		22. January 2018	
MA#				MA001426394					
Package				PG-TSSOP-8-1		Weight*		25.70 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.877	3.41	3.41	34137	34137	
leadframe	non noble metal	magnesium	7439-95-4	0.016	0.06		627		
	inorganic material	silicon	7440-21-3	0.070	0.27		2718		
wire	non noble metal	nickel	7440-02-0	0.322	1.25		12544		
	non noble metal	copper	7440-50-8	10.337	40.23	41.81	402259	418148	
	noble metal	palladium	7440-05-3	0.001	0.00		43		
encapsulation	non noble metal	copper	7440-50-8	0.109	0.42	0.42	4244	4287	
	organic material	carbon black	1333-86-4	0.038	0.15		1483		
	plastics	epoxy resin	-	1.233	4.80		47965		
leadfinish	inorganic material	silicondioxide	60676-86-0	11.437	44.51	49.46	445039	494487	
	noble metal	gold	7440-57-5	0.007	0.03		274		
	noble metal	palladium	7440-05-3	0.007	0.03		274		
	noble metal	silver	7440-22-4	0.007	0.03		274		
plating	non noble metal	nickel	7440-02-0	0.331	1.29	1.38	12885	13707	
	noble metal	palladium	7440-05-3	0.006	0.02		238		
	noble metal	silver	7440-22-4	0.006	0.02		238		
	noble metal	gold	7440-57-5	0.006	0.02		238		
glue	non noble metal	nickel	7440-02-0	0.288	1.12	1.18	11196	11910	
	plastics	acrylic resin	-	0.120	0.47		4665		
	noble metal	silver	7440-22-4	0.479	1.87	2.34	18659	23324	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com